



IEEE MTT-S International Conference on Microwave Acoustics & Mechanics

July 13–15, 2020, Munich, Germany

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Venue

Rohde & Schwarz
Training Centre Munich

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Call for Papers

The International Conference on Microwave Acoustics & Mechanics (IC-MAM) represents a unique and unprecedented opportunity to bring together researchers and practitioners of different background (materials scientists, physicists, microwave engineers and process technologists), to share the most recent advances in new materials and manufacturing processes as well as components and devices, which represent the key for the development of future RF, microwave, mm-wave and THz devices, circuits and systems based on RF-MEMS and Acoustics. IC-MAM is organized by the IEEE Microwave Theory and Techniques Society (MTT-S) and features an exciting technical program and invited talks by worldwide recognized experts of RF-MEMS and BAW/SAW technologies.

Conference Topics

Perspective authors are cordially invited to submit papers in all areas of Microwave Acoustics and RF MEMS including but not limited to:

- Acoustic/MEMS Device Applications
- Acoustic/MEMS Device Design
- Acoustic/MEMS Device Modeling
- Materials & Propagation
- Advances in Filter and Multiplexer Technology
- SAW and BAW Sensor Devices and Applications
- Multi-Band RF Modules for Multi-Standard/-Mode Systems
- Fusion of Major Transmit and Receive Functionality in Single Modules
- Tunable & Reconfigurable Devices, like Bulk and Thin-film Components and Devices, e.g., based on Ferroelectrics, Phase-Change Materials

Submitted papers should be three to four pages in length. Authors must adhere to the format of the IEEE conference paper template.

Submission deadline:	April 13, 2020
Notification of acceptance:	May 11, 2020
Final paper submission:	May 27, 2020
Conference date:	July 13–15, 2020

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